

■ FEATURES

- Low profile package
- Ideal for automated placement
- Glass passivated chip junction
- High forward surge capability
- Super fast reverse recovery time
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C

■ TYPICAL APPLICATIONS

For use in high frequency rectification of power supplies, inverters, converters, and freewheeling diodes for consumer and telecommunication.

■ MAXIMUM RATINGS

- **Package:** DO-214AA (SMB)
Molding compound meets UL 94 V-0 flammability rating, RoHS-compliant, halogen-free
- **Terminals:** Tin plated leads, solderable per J-STD-002 and JESD22-B102
- **Polarity:** Cathode line denotes the cathode end

■ MECHANICAL DATA (T_a=25°C Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	HS1AB	HS1BB	HS1DB	HS1FB	HS1GB	HS1JB	HS1KB	HS1MB
Device marking code			HS1AB	HS1BB	HS1DB	HS1FB	HS1GB	HS1JB	HS1KB	HS1MB
Repetitive peak reverse voltage	VRRM	V	50	100	200	300	400	600	800	1000
Average rectified output current @60Hz sine wave, resistance load, TL (Fig.1)	I _O	A	1.0							
Surge(non-repetitive)forward current @60Hz half-sine wave,1 cycle, T _a =25°C	I _{FSM}	A	30							
Storage temperature	T _{stg}	°C	-55~+150							
Junction temperature	T _j	°C	-55~+150							

■ ELECTRICAL CHARACTERISTICS (T_a=25°C Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	TEST CONDITIONS	HS1AB	HS1BB	HS1DB	HS1FB	HS1GB	HS1JB	HS1KB	HS1MB
Maximum instantaneous forward voltage drop per diode	V _F	V	I _{FM} =1.0A	1.0			1.3		1.7		
Maximum reverse recovery time	t _r	ns	I _F =0.5A, I _R =1.0A, I _{rr} =0.25A	50					75		
Maximum DC reverse current at rated DC blocking voltage per diode @ V _{RM} =VRRM	I _{RRM}	μA	T _a =25°C	5.0							
			T _a =125°C	100							

■ THERMAL CHARACTERISTICS (T_a=25°C Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	HS1AB	HS1BB	HS1DB	HS1FB	HS1GB	HS1JB	HS1KB	HS1MB
Typical Thermal resistance	R _{θJ-A} ⁽¹⁾	°C/W	60 ⁽¹⁾							
	R _{θJ-L} ⁽¹⁾		15 ⁽¹⁾							

Note: (1) Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.3" x 0.3" (8.0 mm x 8.0 mm) copper pad areas

■ CHARACTERISTICS (TYPICAL)

FIG.1: I_o-T_L Cure

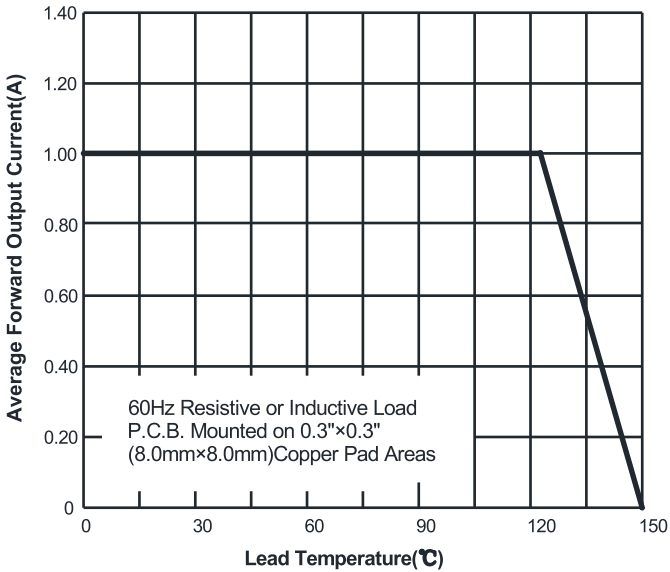


FIG.2: Forward Surge Current Capability

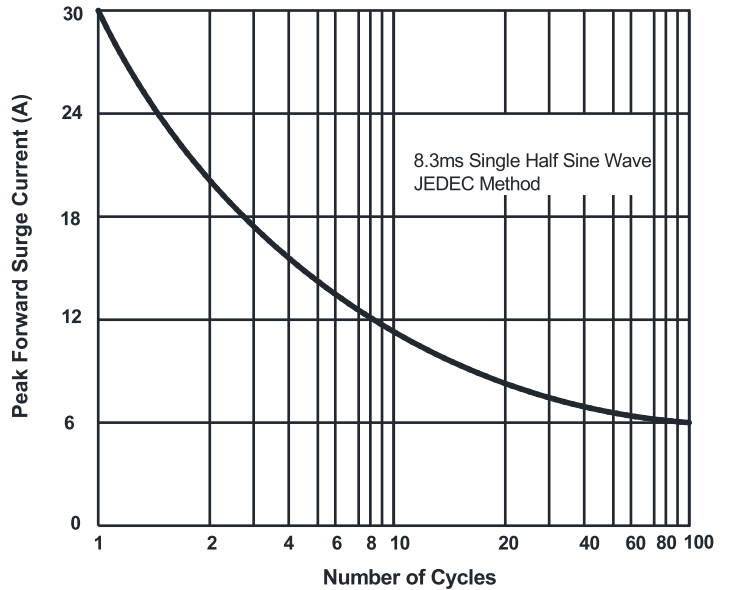


FIG.3: Typical Forward Characteristics

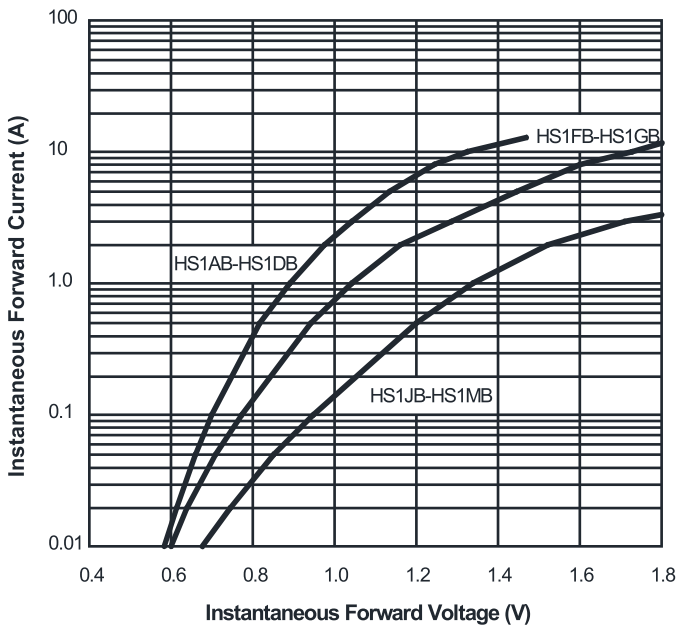


FIG.4: Typical Reverse Characteristics

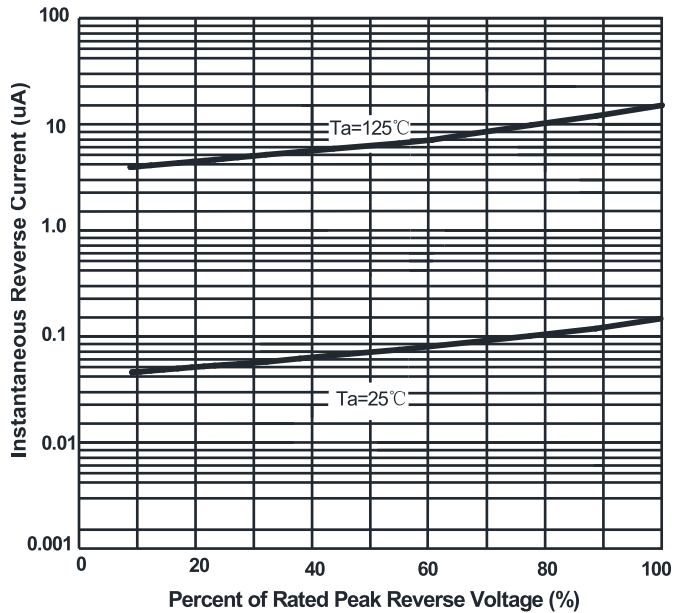
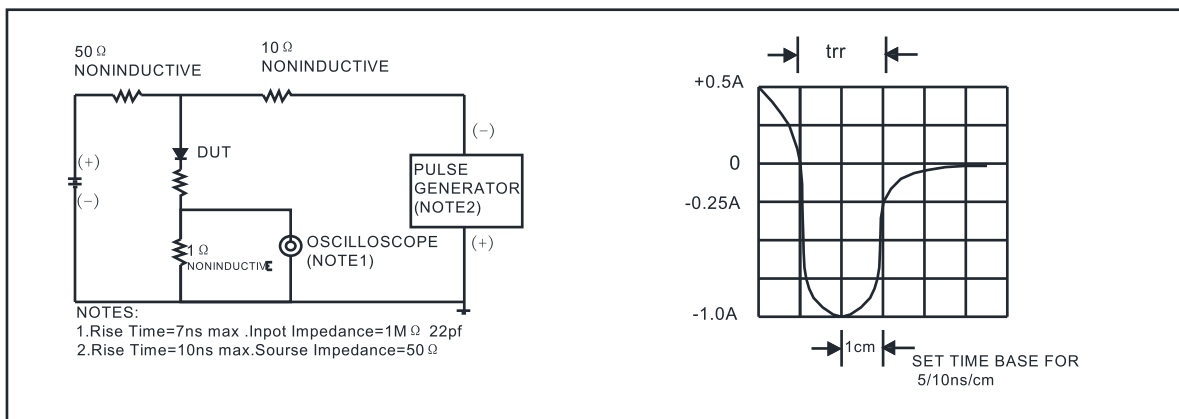


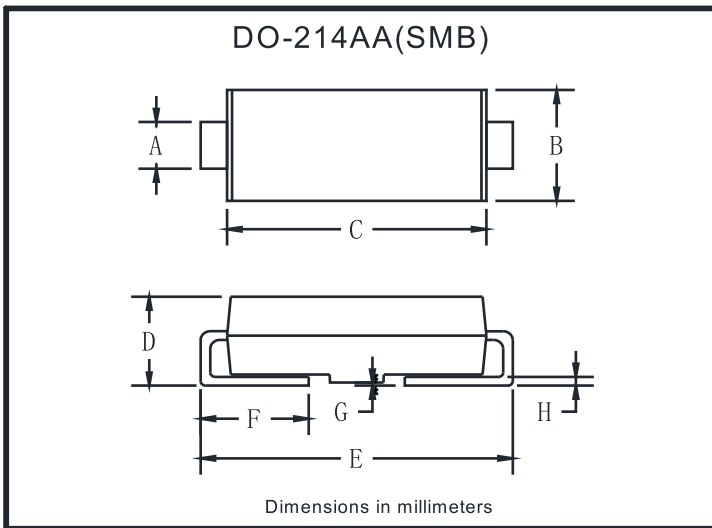
FIG.5: Diagram of circuit and Testing wave form of reverse recovery time



■ **ORDERING INFORMATION (EXAMPLE)**

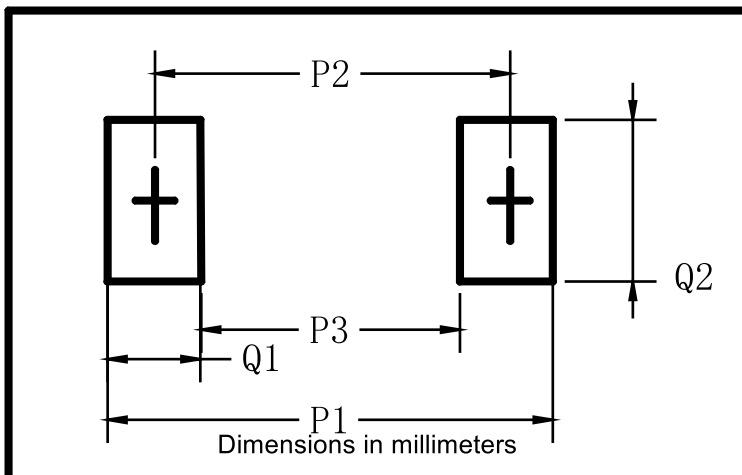
PREFERRED P/N	PACKING CODE	UNIT WEIGHT(g)	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
HS1AB-HS1MB	Omit for Standard	Approximate 0.096	3000	6000	48000	13" reel
HS1AB-HS1MB	X07	Approximate 0.096	750	3000	24000	7" reel

■ **OUTLINE DIMENSIONS**



DO-214AA(SMB)		
Dim	Min	Max
A	1.85	2.15
B	3.30	3.94
C	4.25	4.75
D	1.99	2.61
E	5.21	5.59
F	0.90	1.41
G	0.10	0.20
H	0.15	0.31

■ **SUGGESTED PAD LAYOUT**



DO-214AA(SMB)	
Dim	Millimeters
P1	6.8
P2	4.3
P3	1.8
Q1	2.5
Q2	2.3